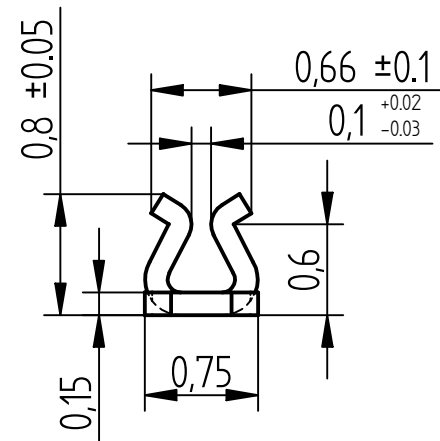
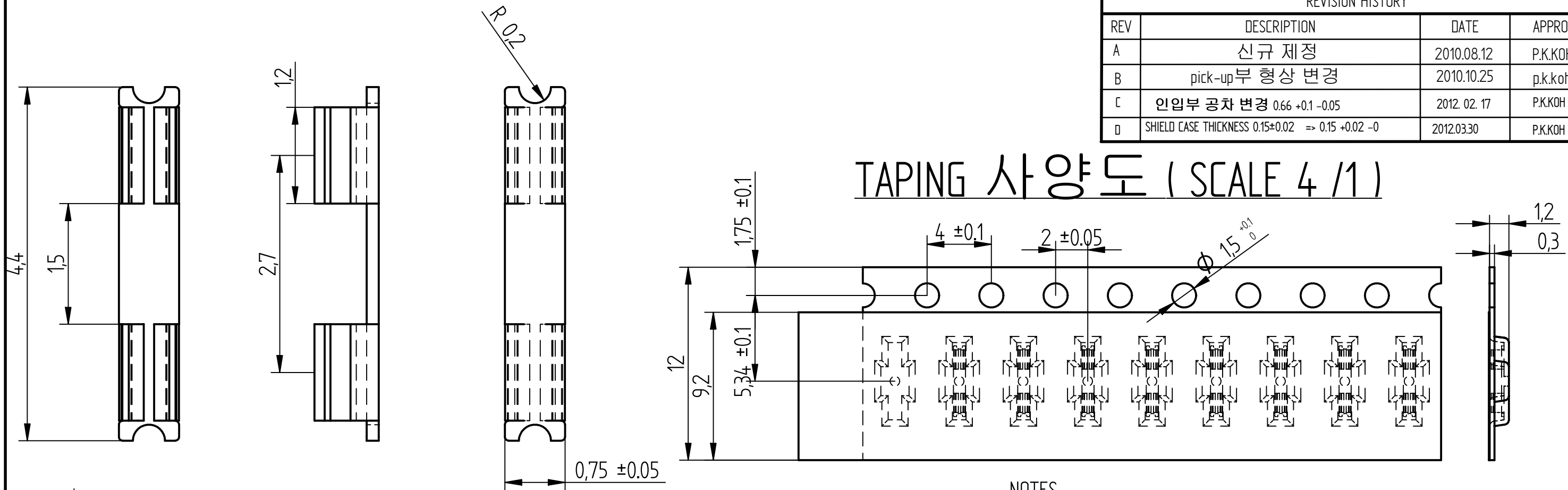


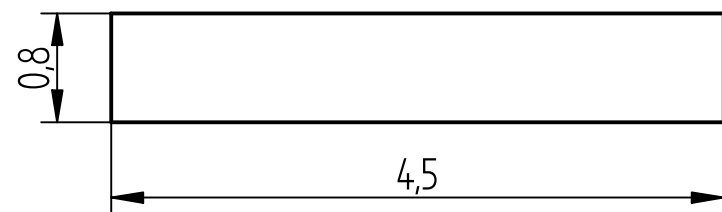
REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVED
A	신규 제정	2010.08.12	P.K.KOH
B	pick-up부 형상 변경	2010.10.25	p.k.koh
C	인입부 공차 변경 0.66 +0.1 -0.05	2012. 02. 17	P.K.KOH
D	SHIELD CASE THICKNESS 0.15±0.02 => 0.15 +0.02 -0	2012.03.30	P.K.KOH

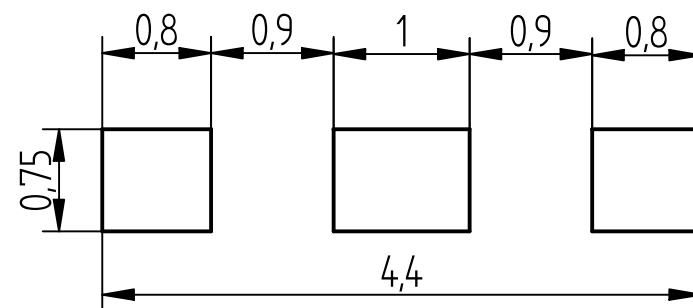
# TAPING 사양도 (SCALE 4 / 1)



SCALE 20/1



RECOMMENDED PCB LAYOUT



RECOMMENDED MASK LAYOUT

NOTES

1. MATERIAL : SUS301
2. MATERIAL THICKNESS : 0.15t
3. FINISHED : Sn(100%) PLATING ON BOTH SIDE  
( Ni 0.5µm Sn 1.27µm )
4. PACKING MATERIALS.  
- REEL : HIPS 0.3t  
- COVER TAPE : PS  
- Q'TY/REEL : 10,000ea
5. AVAILABLE SHIELD CASE THICKNESS : 0.15 +0.02 -0
6. CONTACT RESISTANCE : MAX 300mmΩ
7. STENCIL THICKNESS : 0.12T
8. Maintain 90°±3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip

DATA	NAME	(주)이노칩테크놀로지 Solution Provider	
APP. 2010.08.12	LEE	TITLE SHIELD CLIP	
CHECK		SIZE A3	DWG NO ICSRC-4408-015SFR
DESIG. 2010.08.12	P.K.KO	FILE NAME: ICSRC-4408-015SFR.dft	REV D
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE ANGLES ± 0.3° 0 ~ 1 ± 0.05 1 ~ 5 ± 0.1 5 ~ 10 ± 0.15		SCALE:	WEIGHT: SHEET 1 OF 1